



COPIES OF PAPERS
ORIGINALLY FILED

2815
PATENT
Docket No.: ACT-311

\$

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2815 Examiner: J. Diaz

Serial No. 09/737,642 Filed: December 14, 2000

In re Application of: Wang

For: METAL-TO-METAL ANTIFUSE STRUCTURE AND FABRICATION METHOD

RECEIVED
JUN 19 2002
TECHNOLOGY CENTER 2800

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail, in an envelope addressed to Director of Patents, Washington, D.C. 20231 on 5/31/02, Signed Reshelle Smith

Reshelle Smith

TRANSMITTAL OF RESPONSE TO OFFICE ACTION/AMENDMENT

Director of Patents
Washington, D.C. 20231

Sir:

Enclosed herewith for filing with respect to the above-identified patent application, please find:

1. Amendment and Response to Office Action dated January 31, 2002;
2. 1 sheet of Red Line Drawings;
3. Request for Extension of Time;
4. Check in the amount of \$110.00 for a large entity for 1 month extension fee.

In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, the Assistant Commissioner is hereby authorized to charge or credit the difference to our Deposit Account No. 50-0612. A duplicate of this page is enclosed.

Dated: 5/30/02

Respectfully submitted,
Sierra Patent Group, Ltd.

Kristin C. Castle
Reg. No.: 47,208

Sierra Patent group, Ltd.
P.O. Box 6149
Stateline, NV 89449
(775) 586-9500



COPY OF PAPERS
ORIGINALLY FILED

Attorney Docket: ACT-311

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Daniel C. Wong

Application No.: 09/737,642

Filed: December 14, 2000

Title: METAL-TO-METAL ANTIFUSE
STRUCTURE AND FABRICATION
METHOD

Group Art Unit:
2815

Examiner:
Jose R. Diaz

Attorney Docket No.: ACT-311

#5/ACT
A
6/27/02
RECEIVED
JUN 19 2002
TECHNOLOGY CENTER 2800

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail, in an envelope addressed to Director of Patents, Washington, D.C. 20231 on 5/31/02. Signed Reshelle Smith
Reshelle Smith

RESPONSE TO OFFICE ACTION

Director of Patents
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed on January 31, 2002, Applicant respectfully requests reconsideration of the present rejections and reexamination of the present application in view of the following remarks.

AMENDMENTS

In the specification:

On page 11, please replace the second full paragraph with the following:

Referring now to FIG. 2D, a masking layer 57 is applied over the top of TEOS layer 56 and vias are formed in the second cap layer 38 in preparation for depositing the upper Cu metal layer 58 including contact regions 42 and 44 and to expose the top surfaces of the upper barrier metal layer 36 and the TaN region 32 over region 16 of the lower Cu metal layer. FIG. 2D shows the structure remaining after the formation of the